

Towards the scalable readout system: FEC electronics for APV25, AFTER and Timepix

J. Toledo

Universidad Politécnica de Valencia

Outline

- **A summary of front-end ASIC interface requirements**
- **A flexible interface front-end card (FEC)**
- **A-card application examples**

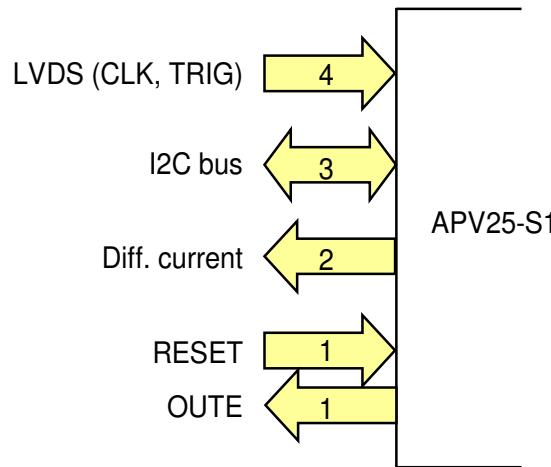
A summary of front-end ASIC interface requirements

A summary of front-end ASIC interface requirements

APV25

Info: "APV25-S1 User Guide Version 2.2", L. Jones (RAL), 5th Sept. 2001.

http://www.te.rl.ac.uk/med/projects/High_Energy_Physics/CMS/APV25-S1/pdf/User_Guide_2.2.pdf



A possible interface to a chip carrier may consist of:

- One analog differential signal input per APV25 chip
- Two LVDS output pairs (clock, trigger)
- One I2C bus (three lines)
- Two additional CMOS I/Os (optional?)

Analogue signals must be sampled at 40 MHz

Signaling levels related to $\pm 1,25\text{V}$ above bias level (GND)

A **voltage level translator** and **isolation circuit** is required to:

- Optically couple the slow signals (I2C bus)
- AC couple the fast signals (clock, trigger)
- Perform **I/V conversion** to 2 Vpp range and **AC coupling** for analog current outputs

Alternatively, optical transceivers can provide the required isolation.

A summary of front-end ASIC interface requirements

TIMEPIX

"TimePix manual v1.0", X. Llopis, CERN, Aug. 2006"

A possible interface to a chip carrier for serial readout may consist of:

- 6x LVDS pairs: enable in&out, fclock in&out, data in&out
- 6x 2.2V CMOS output signals: reset, shutter, mo, m1, polarity, enable_tpulse

Signaling levels related to +2.2V power. So, **level translators** are needed in the FEC.

...though we would need more signals to...

- To allow pixel calibration we need 1xCMOS out, 1x **analog out**, 1x **calibration generator**
- To allow chip's internal DAC monitoring, we need 1x **analog input** per chip
- To substitute any of the TIMEPIX internal DACs, we need **1x analog out**
- To allow the test of (121,0) and (122,0) special pixels, 1+Nx8 more signals are needed

A summary of front-end ASIC interface requirements

TIMEPIX readout via MUROS2

"MUROS2 User's manual", D. San Segundo Bello, NIKHEF, Jul. 2003

The FEC can replace the National Instruments DIO-653X card. This requires 32 I/O lines:

- 15 control lines (3.3V TTL/CMOS)
- 1 CLOCK signal (3.3V TTL/CMOS)
- 16-bit Data bus (3.3V TTL/CMOS)

Additional signals are optional and include a shutter signal, a shutter monitor signal and an external clock (to override the MUROS2 board clock)

FEC should also provide +5V power (max. 1 A). This is not really required, as the MUROS2 board can use an additional +5V input.

We may also need an **analog multiplexer** to switch between 2 **DAC outputs** to produce sharp transitions.

A summary of front-end ASIC interface requirements

AFTER readout via T2K electronics

"T2K TPC Read-out Electronics Digital Front-End Mezzanine Card", Denis Calvet, CEA Saclay, Jul. 2008

T2K's front-end card –named FEC- has 4 AFTER chips and a 4-ch AD9229 ADC.

This board is designed to interface a FEM module using 43 signals + power and ground and a FX2CA-80P-1.27DSAL connector from Hirose (FEM side):

- 8 LVDS pairs
- 17 CMOS 3.3V outputs
- 5 CMOS 3.3V inputs
- 2 CMOS 3.3V bidirectional signals

Some of these signals would require **special circuitry** in the FEC (like tie to ground, pull-up or pull-down resistors, or R-2R summing circuits to produce voltage steps)

A summary of front-end ASIC interface requirements

Summary (signal directions seen from FEC)

Type	AFTER T2K card	TIMEPIX	MUROS2	APV25	ADC card
LVDS.IN	6	3	-	-	-
LVDS.OUT	2	3	-	2	-
I2C bus	1	-	-	1	1
DIG.OUT	15	6	32	2	
DIG.IN	5	-		-	
DIG.BIDIR	2	-		-	-
ANALOG.IN	-	1/chip	-	1/chip	16
ANALOG.OUT	-	3	-	-	-
SIGNALING	3.3V	2.2V	5V	$\pm 1.25V$	

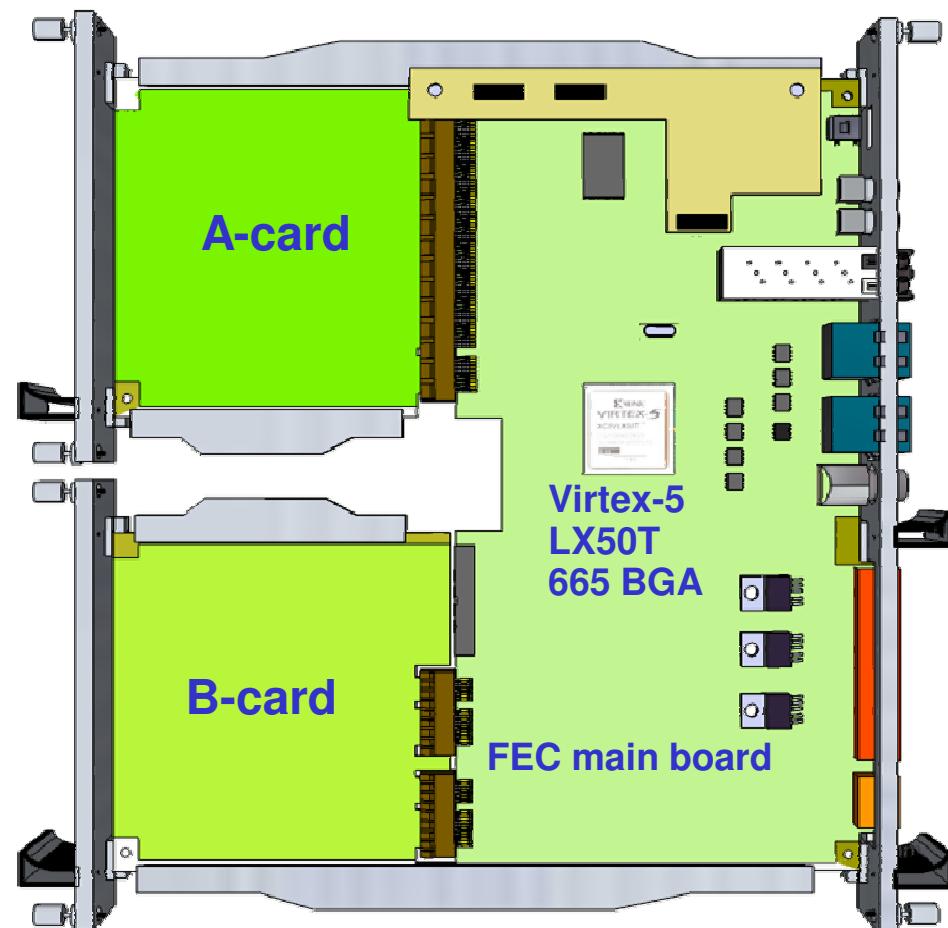
TIMEPIX: charge-sharing test signals have not been included

- Very different interface and circuitry requirements: voltage regulators, reference levels, connectors and specific circuitry (like summing circuits, isolation, I/V, analog multiplexer,...)
- Even if we could address each specific design issue in a common interface circuitry, there is no flexibility to use other ASICs
- ¿Is there a better solution?  Yes, a modular FEC

A flexible interface front-end card (FEC)

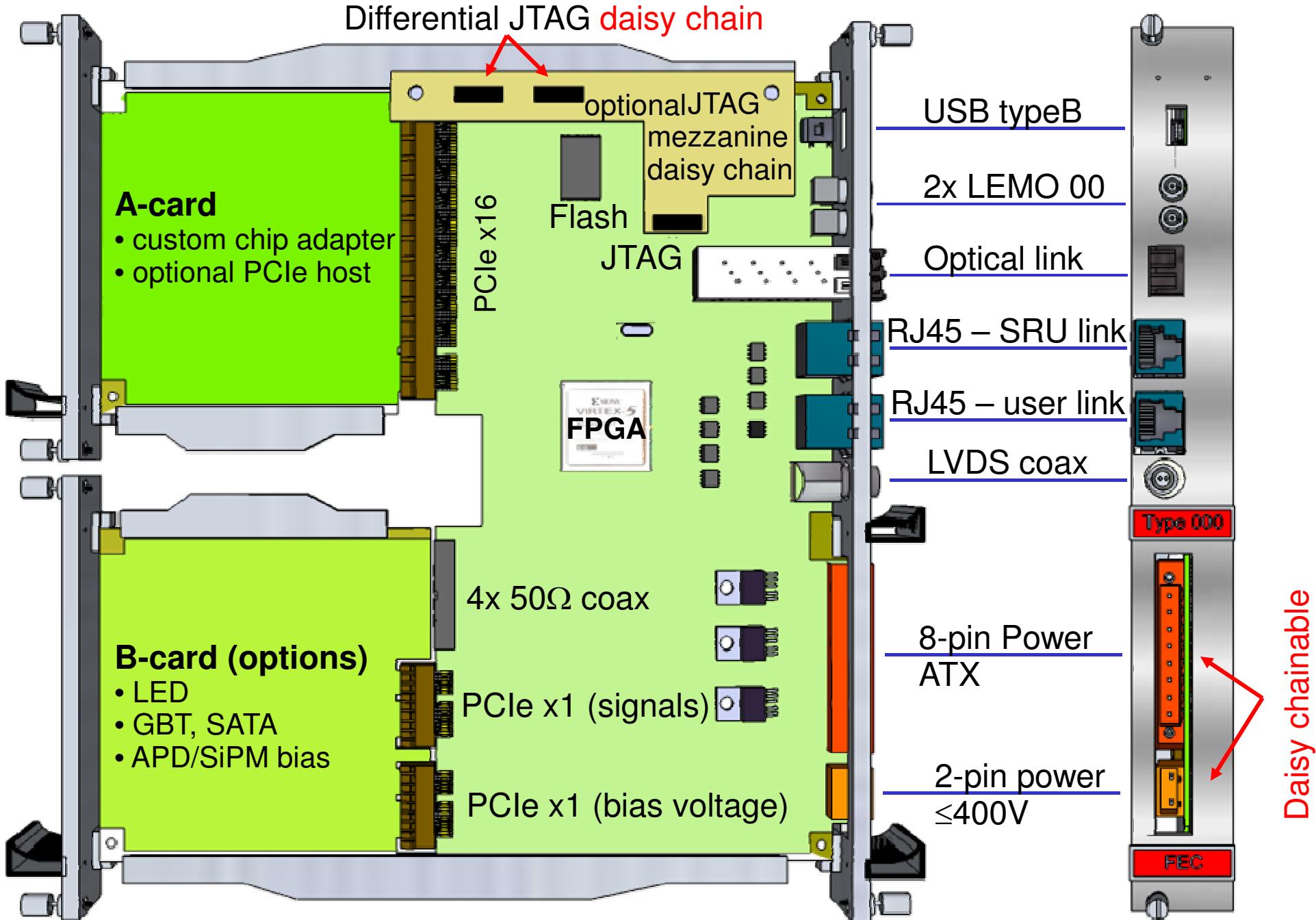
A flexible interface front-end card (FEC)

- 6U module composed of a 6Ux120mm FEC main board and two 3Ux100mm adapter cards
- Module fits on standard 6Ux220mm chassis, with added 100mm card guides
- Front panel (two 3U) is application specific
- Back panel (6U) for power and I/O (DAQ, clock, trigger, control)

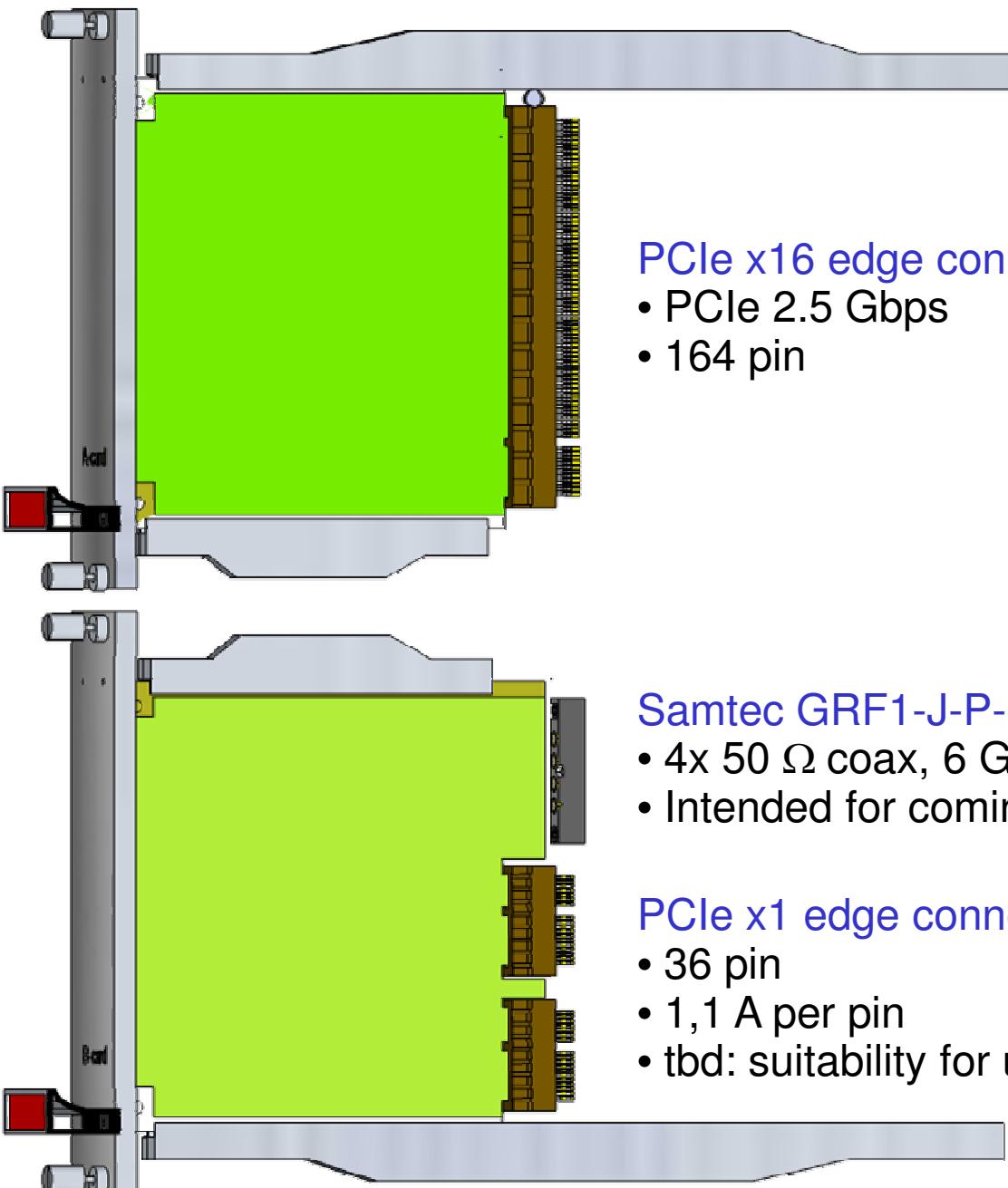


- An application-specific **adapter card (A-card)** includes voltage level translators, DACs, ADCs, voltage regulators, isolation, LVDS drivers and connectors
 - An **optional second adapter card (B-card)** for additional features (APD/SiPM bias control, LED calibration pulsers, high-speed interfaces,...)
- A common **FEC main board** with:
 - FPGA connected to all signal I/O connectors
 - FPGA remote programming from JTAG daisy chain, optical link or SRU conn
 - ATX power conn and voltage regulators
 - Optional APD/SiPM bias voltage conn

A flexible interface front-end card (FEC)

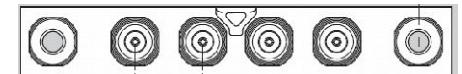


A flexible interface front-end card (FEC)



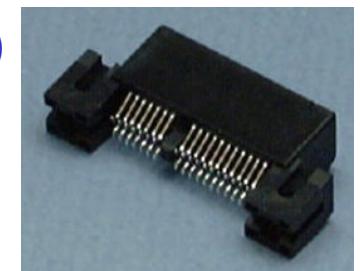
PCIe x16 edge connector (straddle mount)

- PCIe 2.5 Gbps
- 164 pin



Samtec GRF1-J-P-04-E-RA-TH1

- 4x 50 Ω coax, 6 GHz
- Intended for coming GBT interface

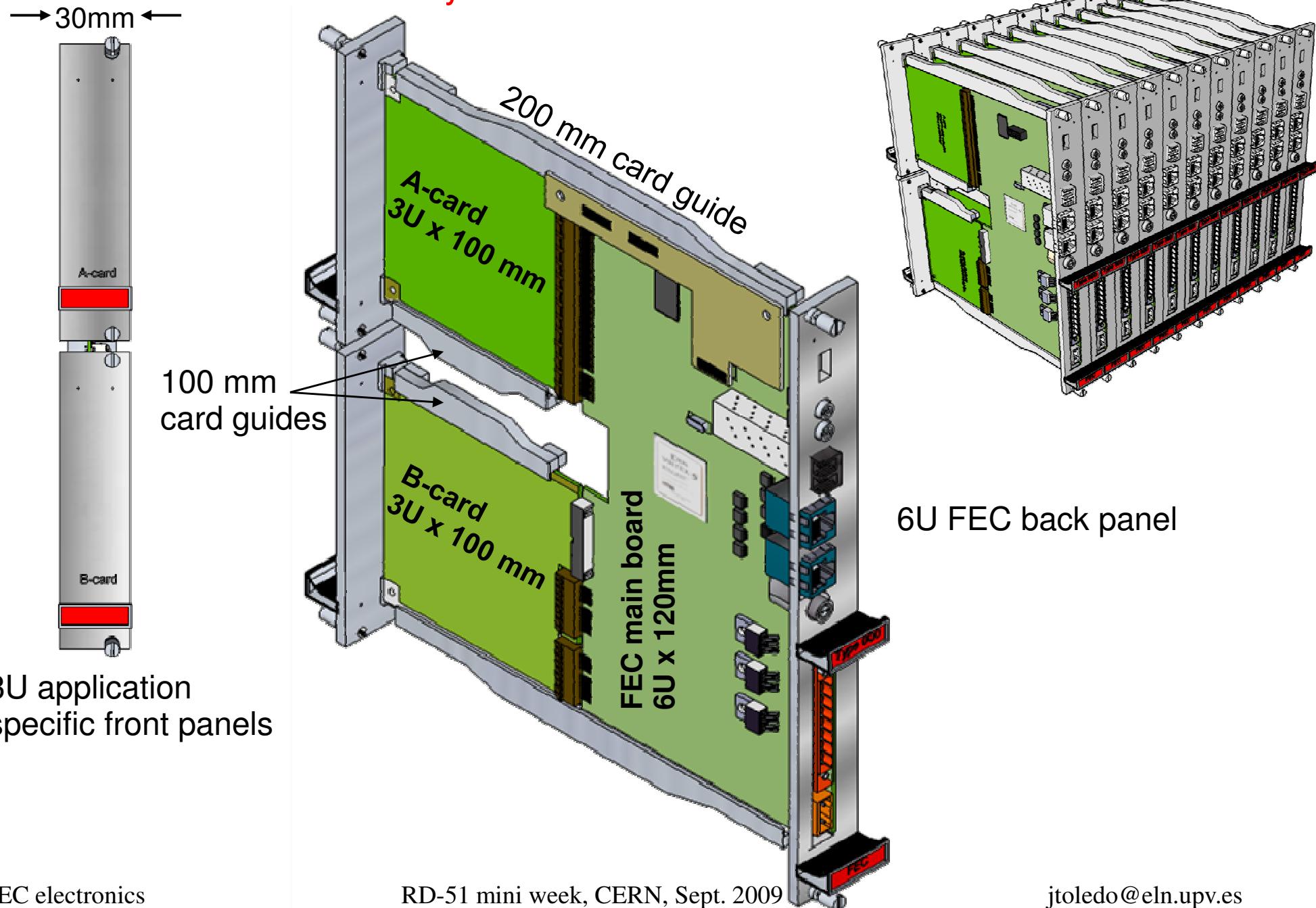


PCIe x1 edge connector (straddle mount)

- 36 pin
- 1,1 A per pin
- tbd: suitability for up to 400V voltages

A flexible interface front-end card (FEC)

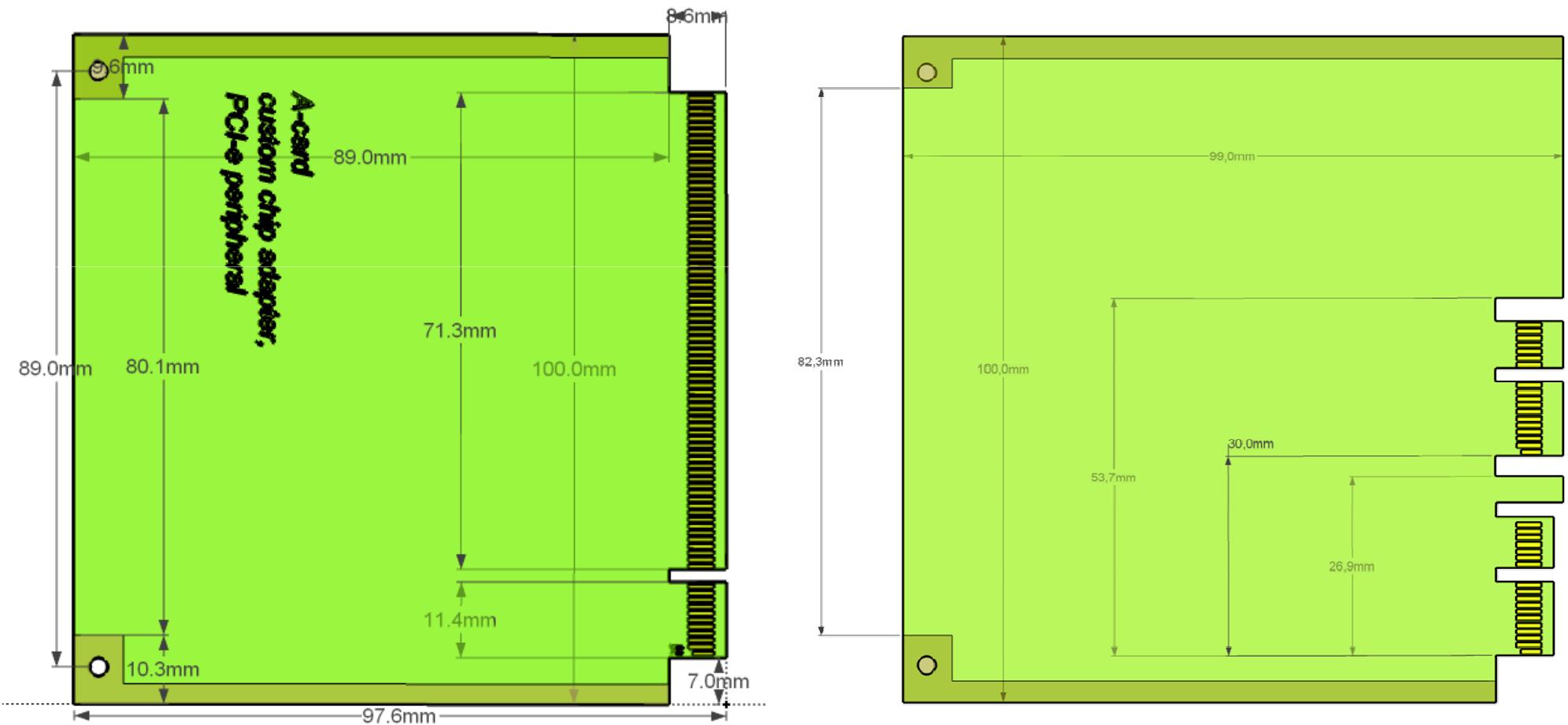
Front-end system of SRS in 6U x 200 Eurocrate



3U application
specific front panels

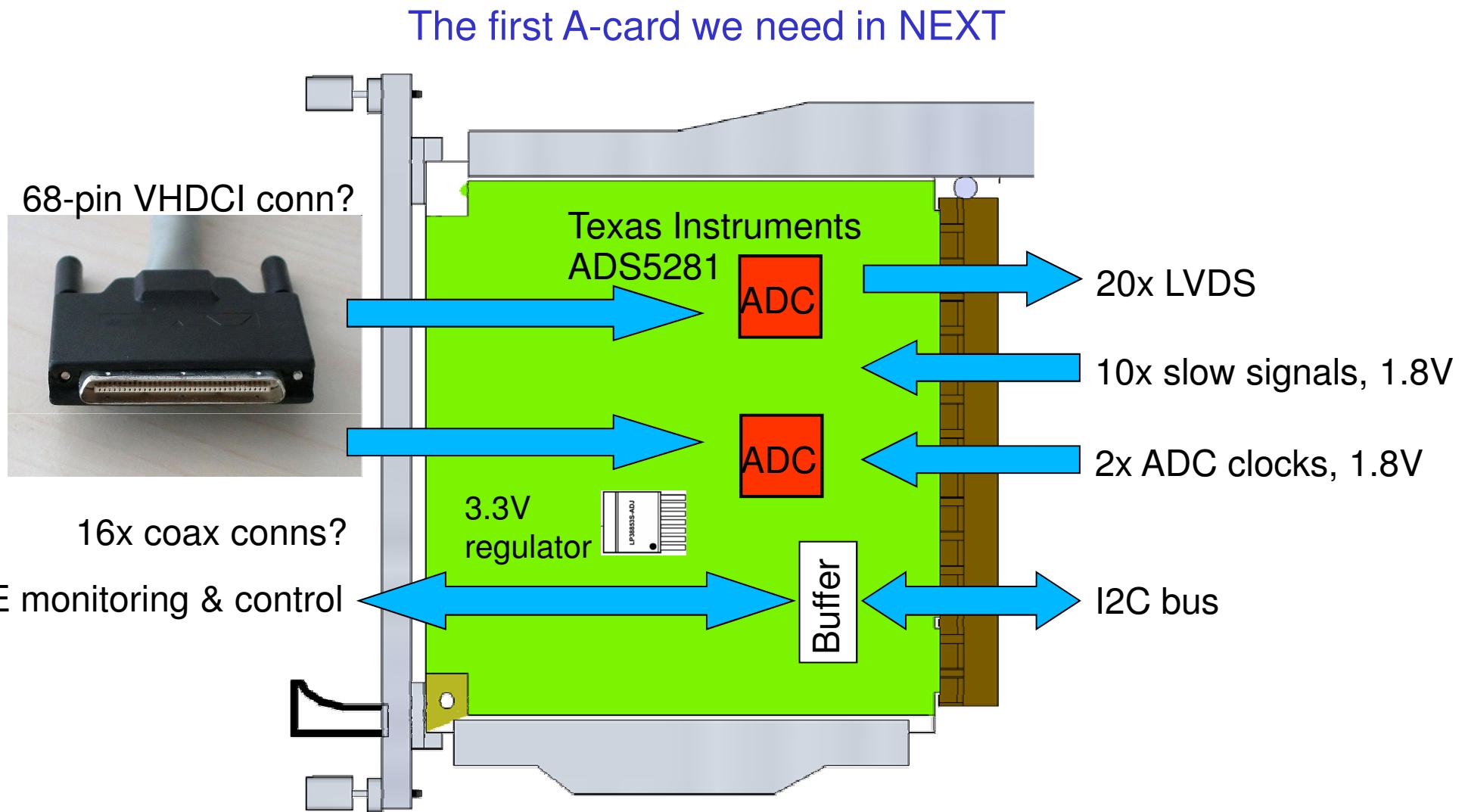
A flexible interface front-end card (FEC)

A-card and B-card mechanical drawings, connector pinout and electrical specs will be made available to allow user developments

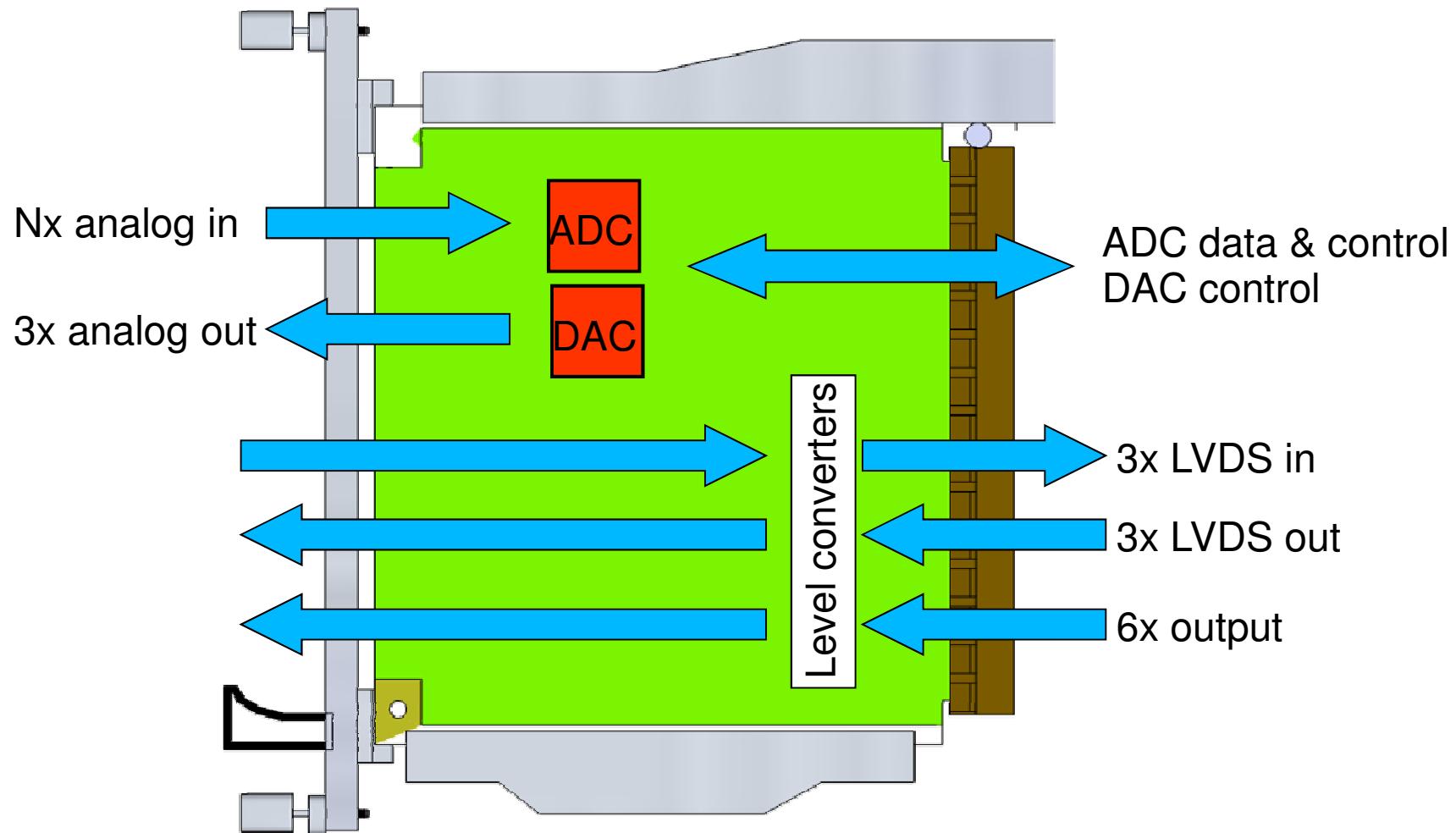


A-card application examples

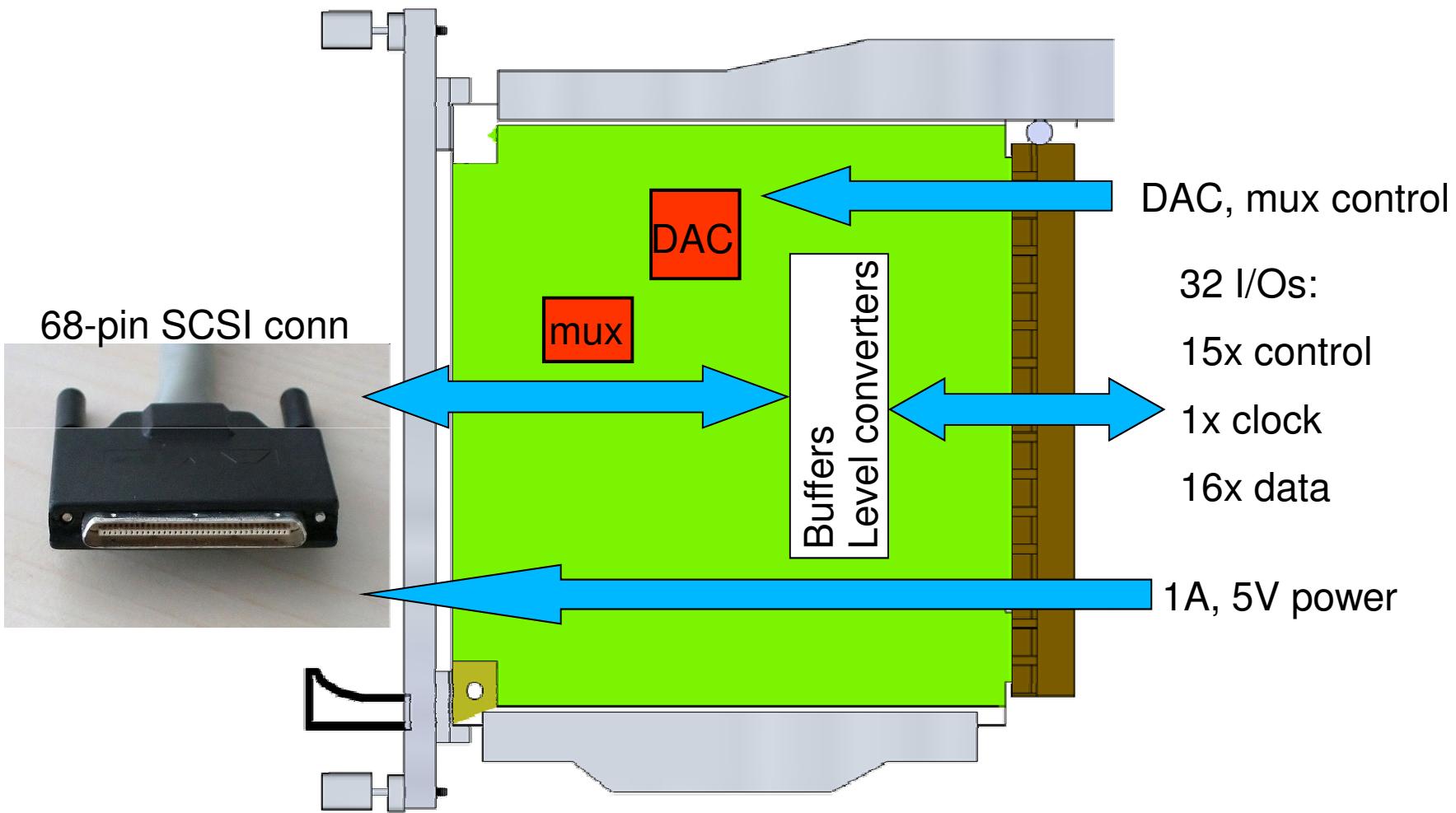
Application example: 16ch 40MHz ADC



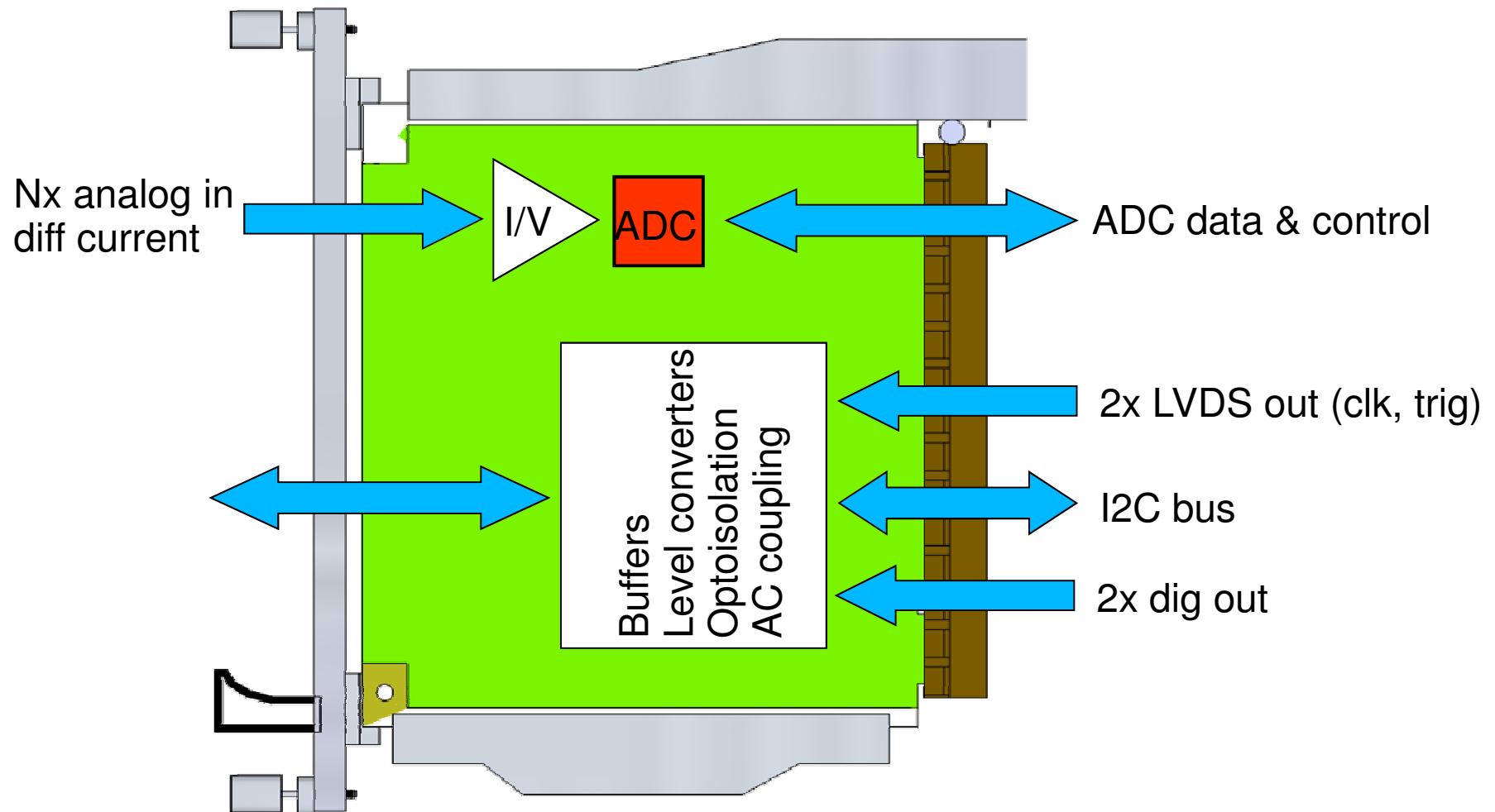
Application example: TimePix



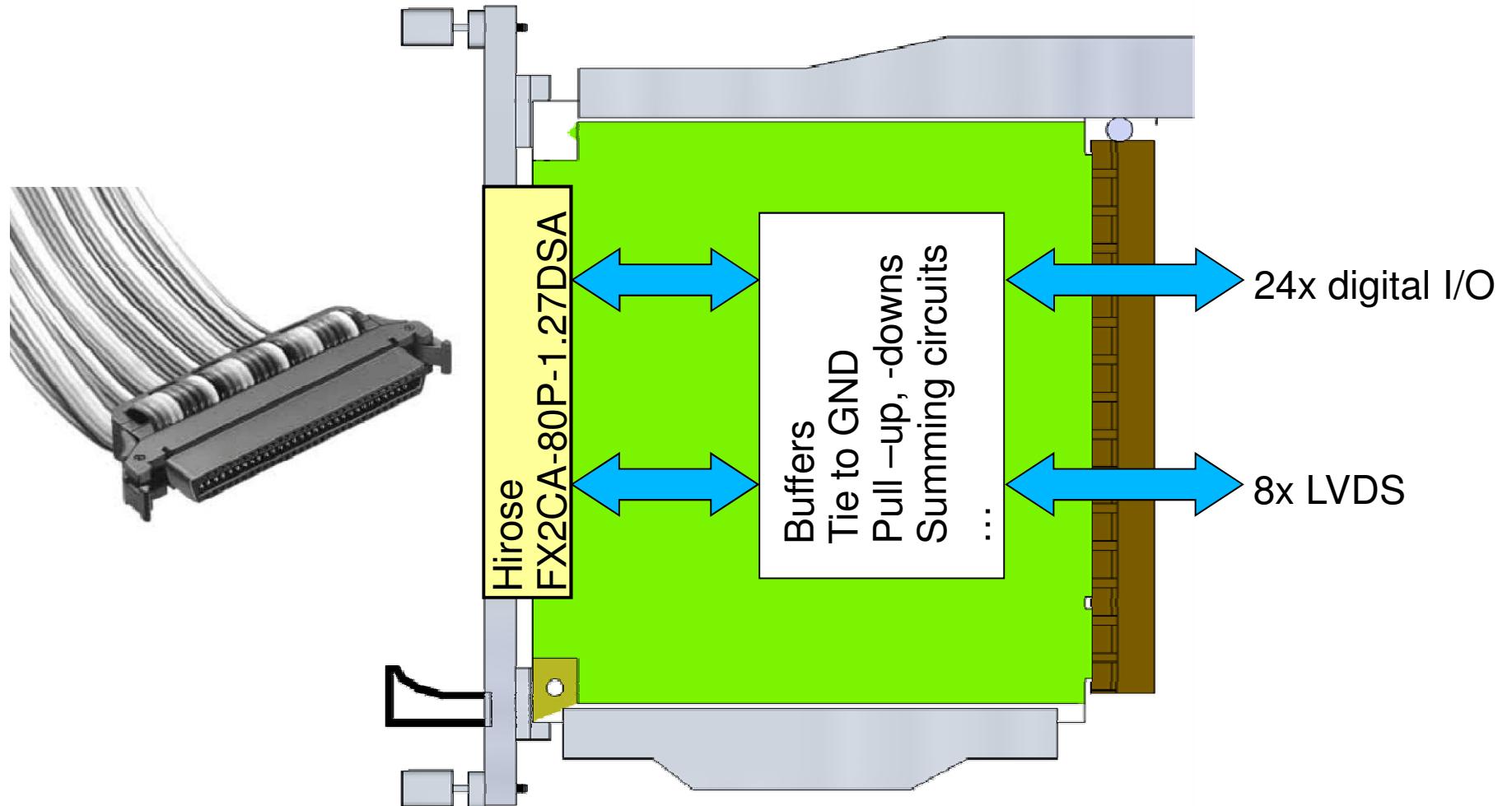
Application example: MUROS2



Application example: APV25



Application example: T2K AFTER



Conclusions

- ASIC interface requirements are too different for a common FEC design
- A modular FEC solution has been proposed for 6U x 220 Eurorates
 - Front panel for FE interface and back panel for power, DAQ, trigger and control
 - A-card for application-specific ASIC interface
 - Optional B-card for other interesting FE features
- A-card, B-card specs to be released for user developments

Thank you !